12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130708001
Qualification of JCAP as an Additional Assembly, Bump, and Test site for Select Devices on WCSP Package
Change Notification / Sample Request

Date: 7/15/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130708001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS22903YFPR	null
TPS22904YFPT	null
TPS22908YZTR	null
TS5A12301EYFPR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130708001	PCN Date:	07/15/2013
Title:	Qualification of JCAP as an Additional Assembly, Bump, and Test site for Select Devices on WCSP Package		
Customer Contact:	PCN Manager	Phone: +1(214)480-6037	Dept: Quality Services
Proposed 1st Ship Date:	10/15/2013	Estimated Sample Availability:	Date Provided at Sample request

Change Type:					
☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of JCAP as an Additional Assembly, Bump, and Test site for Select Devices on WCSP Package. Assembly differences are shown in the following table:

Group 1 Device: Current Assembly – TI Clark		
	Clark-AT	**JCAP-AT**
Bump Site	Clark-BP	JCAP-FAB
Solder Ball	4207848	MA22008110

Group 2 Device: Current Assembly – SCSAT		
	SCS-AT	**JCAP-AT**
Bump Site	SCS-BP	JCAP-FAB
Solder Ball	014461D	MA22008110

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
SCS-AT	Assembly Site Origin (22L)	ASO: STS
Clark-AT	Assembly Site Origin (22L)	ASO: QAB
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label to show code location only - not actual product label

Assembly Site Code: Clark-AT=I, JCAP-AT=P

Product Affected:

Group 1 Device: Current Assembly – TI Clark	
TPS22908YZTR	TPS22908YZTT

Group 2 Device: Current Assembly – SCSAT			
TPS22903YFPR	TPS22904YFPR	TPS22904YFPT	TS5A12301EYFPR

Qualification Data – Group 1 Device

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : TS3DS26227YZT (MSL1-260C)

Package Construction Details

Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	12-YZT, WCSP/DSBGA	**Bump Diameter:**	0.25mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
**Steady-state Life Test	150C (300 Hrs)	116/0	116/0	116/0
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-55C/+125C (1000 Cyc)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg site specifications)	Pass	Pass	Pass
Moisture Sensitivity	MSL1-260C	12/0	12/0	12/0
** Moisture Preconditioning (MSL1-260C)				

Qualification Data – Group 2 Device

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : CD3239 (MSL1-260C)

Package Construction Details

Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	25-YFP, WCSP/DSBGA	**Bump Diameter:**	0.25mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot 1	Lot 2	Lot 3
**Steady-state Life Test	150C (300 Hrs)	116/0	116/0	116/0
**High Temp. Storage Bake	150C (1000hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-55C/+125C (1000 Cyc)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg site specifications)	Pass	Pass	Pass
Moisture Sensitivity	MSL1-260C	12/0	12/0	12/0
** Moisture Preconditioning (MSL1-260C)				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com